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(12) **United States Design Patent** (10) **Patent No.:** **US D930,588 S**
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(54) **BATTERY PROTECTION CIRCUIT MODULE PACKAGE**

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(30) **Foreign Application Priority Data**

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(51) **LOC (13) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/119**

(58) **Field of Classification Search**
USPC D13/103, 118, 119, 120, 121, 182, 184
CPC H02H 7/18; H02J 7/0029; H01M 10/425;
H01M 10/4257; H01M 10/48
See application file for complete search history.

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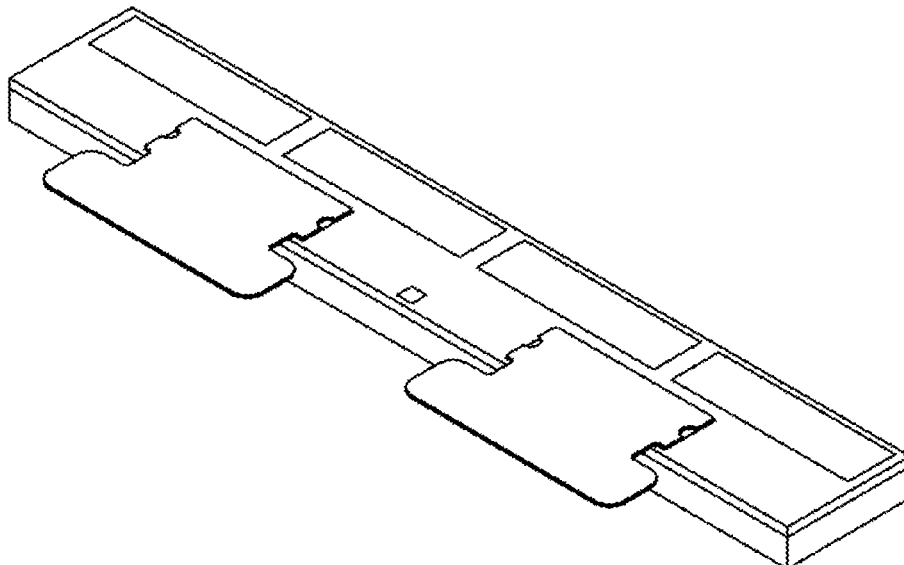
(57) **CLAIM**

We claim the ornamental design for a battery protection circuit module package, as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of a battery protection circuit module package showing our new design;
FIG. 2 is a front elevational view thereof;
FIG. 3 is a rear elevational view thereof;
FIG. 4 is a left side elevational view thereof;
FIG. 5 is a right side elevational view thereof;
FIG. 6 is a top plan view thereof; and,
FIG. 7 is a bottom plan view thereof.

1 Claim, 3 Drawing Sheets



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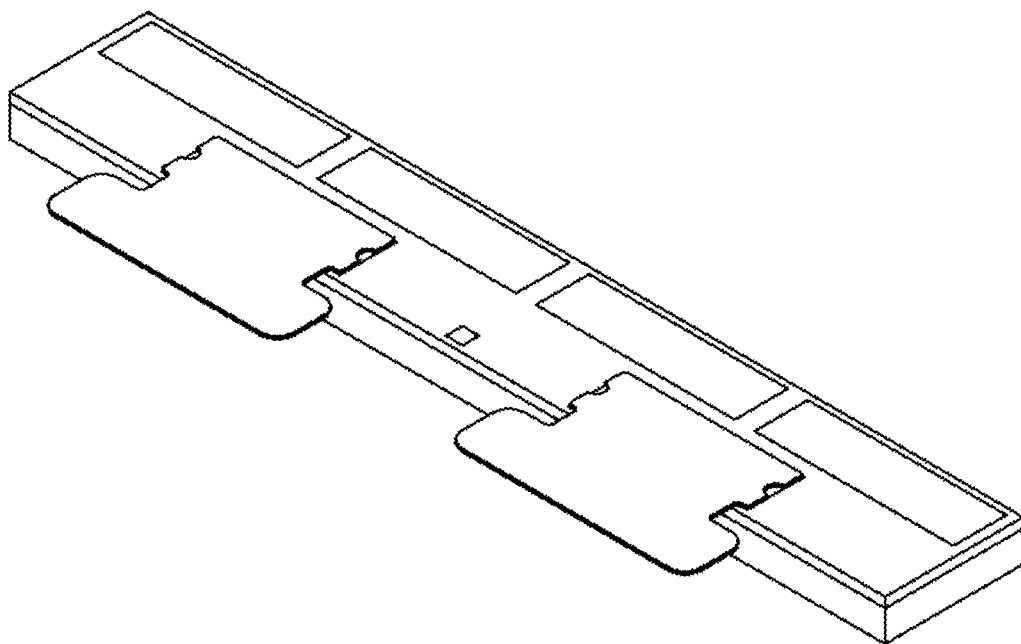


FIG. 1



FIG. 2

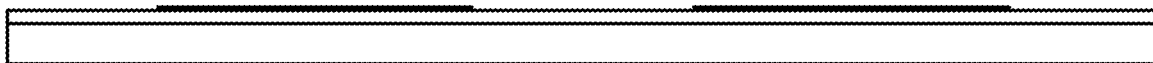


FIG. 3



FIG. 4

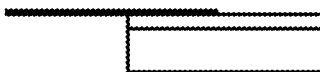


FIG. 5

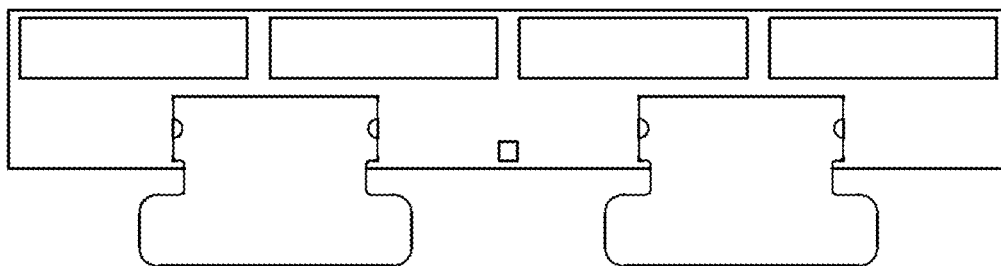


FIG. 6

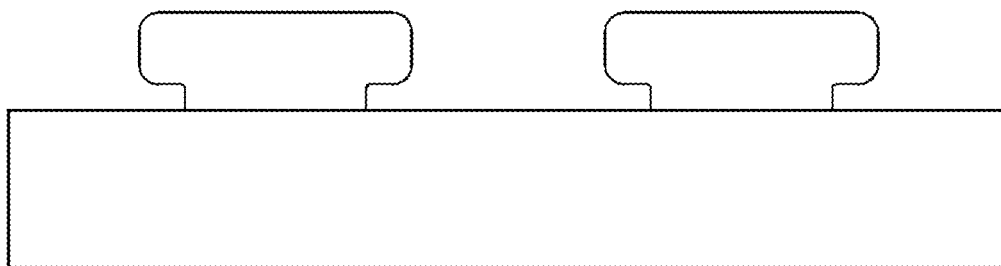


FIG. 7